

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A method of packaging a die comprising:
electrically connecting the die to a substrate;
underfilling the space between the die and the substrate using a capillary underfill;
placing a compressible film onto a backside surface of the die;
compressing the film; and
placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill.
2. (Currently Amended) The method of claim 1 further comprising removing the compressible film. ~~wherein the die includes a backside surface and four sidewall surfaces, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill includes encapsulating the backside surface and the four sidewall surfaces with the pressurized material.~~
3. (Original) The method of claim 2 wherein the pressurized material is a different material than a material associated with underfilling the space between the substrate and the die.
4. (Original) The method of claim 1 wherein the pressurized material associated with placing a pressurized material in contact with at least a portion of the die is a different material than a material associated with underfilling the space between the substrate and the die.
5. (Currently Amended) ~~The method of claim 1~~ A method of packaging a die comprising:
electrically connecting the die to a substrate;
underfilling the space between the die and the substrate using a capillary underfill; and
placing a pressurized material in contact with at least a portion of the die and the
substrate after the capillary underfill, wherein the die includes a backside surface and four

sidewall surfaces, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill excludes placing the pressurized material on the backside surface of the die.

6. (Currently Amended) The method of claim ~~[[1]] 5 wherein the die includes a backside surface and four sidewall surfaces~~, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill further includes:

placing a film on the backside of the die; and

placing the pressurized material on the four sidewall surfaces of the die.

7. (Currently Amended) The method of claim ~~[[1]] 5 wherein the die includes a backside surface and four sidewall surfaces~~, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill further includes:

placing a film on the backside of the die;

pressurizing the film;

placing the pressurized material on the four sidewall surfaces of the die; and

removing the film.

8. (Original) The method of claim 7 wherein the pressurized material is a heated epoxy and wherein the film is removed after the heated epoxy is cured.

9. (Original) The method of claim 7 further comprising transferring heat from the backside surface of the die with a heat transfer device in contact with the backside surface of the die.

10. - 21. (Canceled)

22. (Currently Amended) The method of claim ~~[[21]] 27~~ wherein the first material is a curable epoxy.

23. (Currently Amended) The method of claim [[21]] 27 wherein a capillary action of the first material is used in underfilling the space between the die and the substrate.

24. (Currently Amended) The method of claim [[21]] 27 wherein the second material is a curable epoxy.

25. (Currently Amended) The method of claim [[21]] 27 wherein placing a second material in contact with at least a portion of the die and the substrate includes encapsulating the die.

26. (Canceled)

27. (Currently Amended) ~~The method of claim 26~~ A method of packaging a die comprising:
attaching the die to a substrate;

underfilling the space between the die and the substrate with a first material; and
placing a second material in contact with at least a portion of the die and the substrate after
underfilling the space between the die and substrate with the first material, wherein placing a
second material in contact with at least a portion of the die and the substrate includes partially
encapsulating the die and, wherein the die includes a backside surface and at least four sidewall surfaces, wherein partially encapsulating the die includes:

placing a film on the backside surface of the die;

applying a force to the film; and

encapsulating the four sidewalls of the die with the second material while leaving the backside surface of the die devoid of the second material.

28. (Original) The method of claim 27 further including removing the film from the backside surface of the die.

29. (Currently Amended) The method of claim [[21]] 27 wherein the die includes a backside surface and at least four sidewall surfaces, wherein placing a second material in contact

with at least a portion of the die and the substrate includes leaving the backside surface of the die devoid of the second material.

30. (Previously Presented) The method of claim 27 further comprising placing a heat sink in thermal communication with the backside surface of the die.

31. (Previously Presented) The method of claim 27 further comprising:
placing a thermally conductive material on the backside surface of the die; and
placing a heat sink onto the conductive material.

32. (Currently Amended) The method of claim [[21]] 27 further comprising etching the device.

33. (Currently Amended) The method of claim [[21]] 27 wherein placing a second material in contact with at least a portion of the die and the substrate further includes pressurizing the second material.

34. (Previously Presented) The method of claim 1 further comprising etching the device.

35. (Previously Presented) The method of claim 1 further comprising:
allowing the underfill material to at least partially cure; and
etching the device.

36. (Previously Presented) The method of claim 5 further comprising placing a thermally conductive material onto the backside surface of the die.

37. (Previously Presented) The method of claim 5 further comprising:
placing a thermally conductive material onto the backside surface of the die; and
placing a heat sink onto the thermally conductive material.

38. (Previously Presented) The method of claim 5 further comprising placing a heat sink in thermal communication with the backside surface of the die.

39. (Previously Presented) The method of claim 1 further comprising placing a heat sink in thermal communication with the die.

40. (Previously Presented) The method of claim 5 further comprising placing another encapsulating material onto the backside surface of the die.